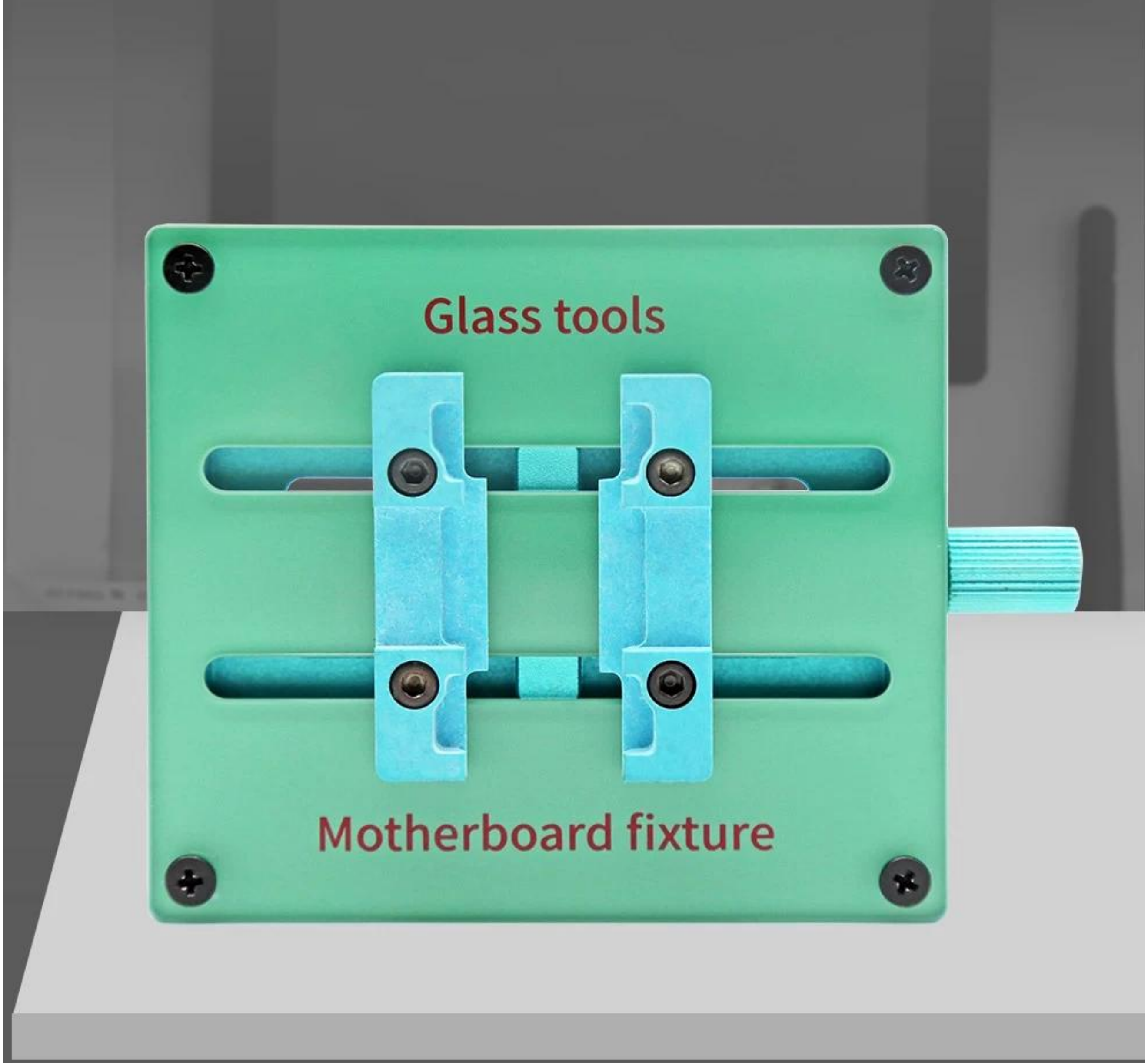
Name: Mobiltelefon Motherboardglasvorrichtung
Modell: BST-189
Material: Aluminiumlegierglas
Glasdicke: 3 mm
Produktgröße: 104*80*20 mm
Paketgröße: 112*84*23 mm
N.W.: 224g
G.W.: 234G

MOBILE PHONE MOTHERBOARD HEAT INSULATING GLASS FIXTURE

Tempered glass / Corrosion resistance / High temperature resistance



Bidirectional bearings

Heat Insulating Glass

Corrosion resistance

Suitable for multiple motherboards

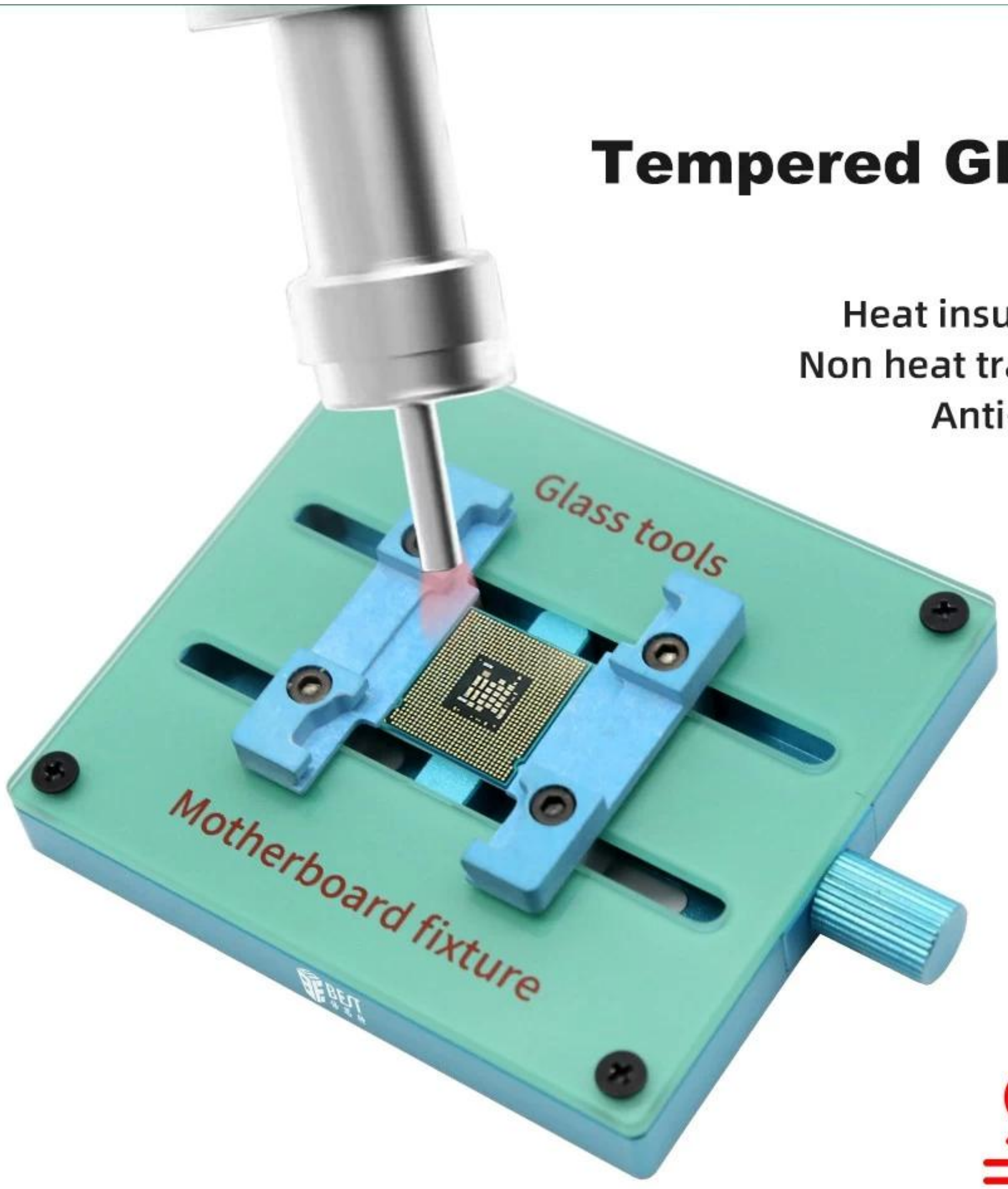
Specifications

Product Name	Motherboard Glass Fixture
Product Model	BST-189
Material	Aluminum alloy+tempered glass
Glass Thickness	3mm
Base Size	90 * 80 mm
Product Size	104 * 80 * 20mm
Package Size	112 * 84 * 23mm
N. W.	224g
G. W.	234g

Tempered Glass

+

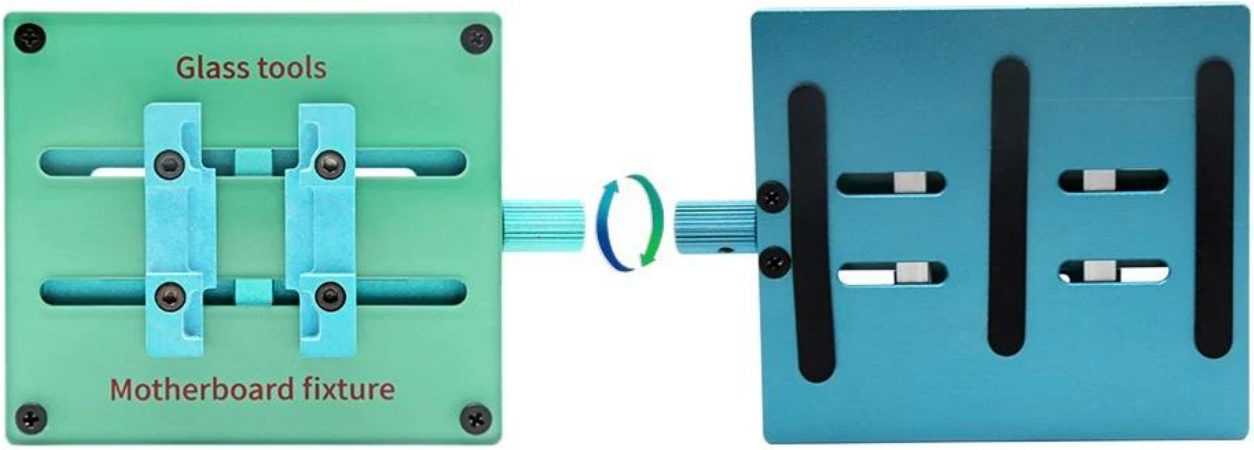
Heat insulation
Non heat transfer
Anti-static



Concealed Screw Arbor

+

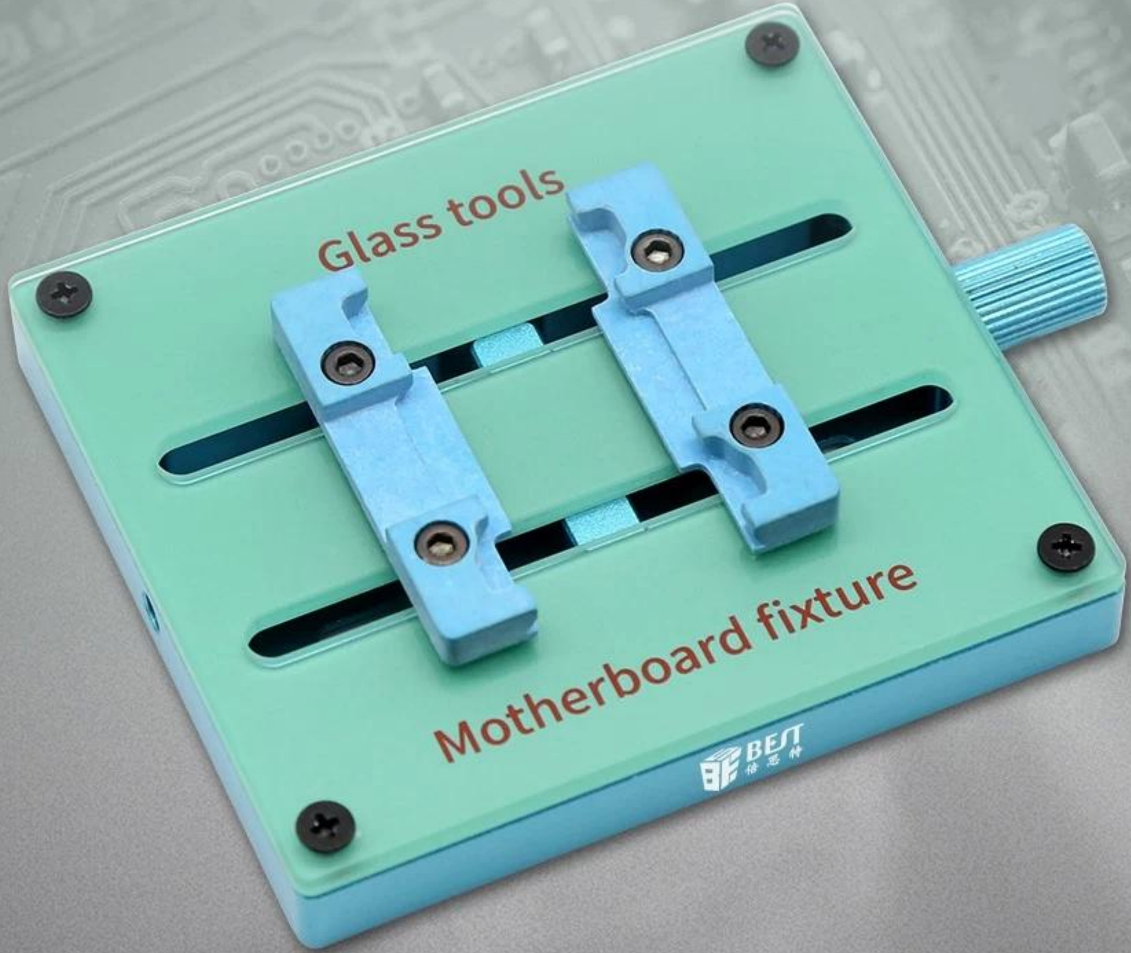
Flexible bidirectional adjustment
More durable and fastening



HEAT INSULATION GLASS

MOTHERBOARD GLASS FIXTURE

BST-189



Product Size